

## Lam (OnTrak) DSS200 Post-CMP Double Sided Scrubber (DSS) Series 2



The Lam (OnTrak) DSS200 Post-CMP Double Sided Scrubber (DSS) is designed to clean wafers using options for a variety of chemical processes, including, but not limited to Post-CMP cleaning. The system is composed of multiple components which operate together to achieve processing requirements for semiconductor wafer cleaning. The major system components include:

- Wet input station for automated wafer loading into the cleaner.
- Brush station #1 is the first brush stations the wafers enters in the processing cycle. The first scrub process is performed on PVA brushes using DI water and dilute cleaning chemistries.
- Brush station #2 is the second brush stations the wafers enters in the processing cycle. This scrub process also uses PVA brushes using DI water and dilute cleaning chemistries.
- The spin station is the third processing station: wafers receive a final rinse, followed by a spin dry in the SRD while a heat lamp assists in the completion of the drying process. This station may also include a dilute chemical dispense prior to final rinse.
- An unload hander/mechanical arm transports wafers out of the spin stations and to the output station.
- The output station contains a wafer indexer that receives the wafers from the transfer arm and loads the clean, dry wafers into a cassette for transfer to the next processing step.

For OnTrak refurbished CMP equipment:  
[info@entrepix.com](mailto:info@entrepix.com)

For OnTrak CMP spare parts and upgrades:  
[parts@entrepix.com](mailto:parts@entrepix.com)

For OnTrak equipment service or maintenance:  
[service@entrepix.com](mailto:service@entrepix.com)

Or Call:  
602-426-8677 (Sales)

### Options:

- Wafer sizes: Configurable for 100 mm, 125 mm, 150 mm and 200 mm
- Remote Electrical Enclosure
- Megasonic Cleaning Unit
- Edge Cleaning in both brush boxes
- Chemical distribution (interchangeable for 2% NH<sub>4</sub>OH, through the brush, 2% NH<sub>4</sub>OH drip (standard configurations), and NH<sub>4</sub>OH through-the brush)
- Through-the-back (TTB) Facilities Hookup
- Through-the-floor (TTF) Facilities Hook up
- Through-the-Front Wafer Load Input Station



## Series 2

### Preventative Maintenance Program

#### Overview

- General Clean and Inspections
- Verify Facilities, Tool Matching
- Replace Brushes and Edge Rollers
- Calibrate Brush Parallelism
- Calibrate Wafer Handling - Smooth Wafer Flow
- Install PM Kit
  - Complete OEM-Specific Kit
  - Customer-Customized Kit
  - Entrepix Recommended Kit
- Tool-Specific Issues Addressed

### Upgrades and Refurbishment

#### Overview

- Idle Flow Retrofit, DI Conservation
- Hastelloy Spin Carriage
- Flat Panel Touch Screen
- Flow Monitoring
- OPTO Interrupt Sensor Upgrade
- Fiber Amplifier Upgrade